

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of :
:
Sasson R. SOMEKH et al. :
:
Serial No. unassigned : Group Art Unit:
:
Filed: herewith : Examiner:

For: MULTI-TOOL CONTROL SYSTEM, METHOD AND MEDIUM

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

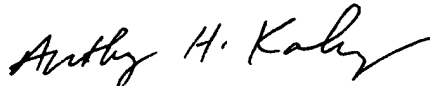
In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of publication indicated for an item is taken from the face of the item, and Applicant reserves the right to prove that the date of publication is in fact different.

The references listed on Sheets 1-19 of Form PTO-1449 were cited by or submitted to the U.S. Patent and Trademark Office in parent application Serial No. 09/469,227, filed December 22, 1999, which is relied upon for an earlier filing date under 35 USC § 120. Copies of these references are not attached under 37 CFR 1.98(d).

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

HALE AND DORR LLP



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Date: Oct 17 2003

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 004393 USA/02/MTCG/PCTRL/JW		SERIAL NO. unassigned	
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				FILING DATE herewith		GROUP	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	3,205,485	09/07/65	Noltingk			10/21/60	
	3,229,198	01/11/66	Libby			09/28/62	
	3,767,900	10/23/73	Chao et al.			06/23/71	
	3,920,965	11/18/75	Sohrwardy			03/04/74	
	4,000,458	12/28/76	Miller et al.			08/21/75	
	4,302,721	11/24/81	Urbanek et al.			05/15/79	
	4,368,510	01/11/83	Anderson			10/20/80	
	4,616,308	10/07/86	Morshedi et al.			12/02/85	
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	5,309,221	05/03/94	Fischer et al.			12/31/91	
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	5,329,463	07/12/94	Sierk et al.			01/13/93	
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	5,787,269	07/28/98	Hyodo			09/19/95	
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	6,036,349	03/14/00	Gombar			07/26/96	
	6,041,270	03/21/00	Steffan et al.			12/05/97	
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	6,078,845	06/20/00	Friedman			11/25/96	
	6,097,887	08/01/00	Hardikar et al.			10/27/97	
	6,108,092	08/22/00	Sandhu			06/08/99	
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	6,148,099	11/14/00	Lee et al.			07/03/97	
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	6,159,075	12/12/00	Zhang			10/13/99	
	6,159,644	12/12/00	Satoh et al.			03/06/96	
	6,161,054	12/12/00	Rosenthal et al.			09/17/98	
	6,169,931	01/02/01	Runnels			06/29/98	
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	6,173,240	01/09/01	Sepulveda et al.			11/02/98	
	6,175,777	01/16/01	Kim			01/16/98	
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	6,178,390	01/23/01	Jun			09/08/98	
	6,183,345	02/06/01	Kamono et al.			03/20/98	
	6,185,324	02/06/01	Ishihara et al.			01/31/95	
	6,191,864	02/20/01	Sandhu			02/29/00	
	6,192,291	02/20/01	Kwon			10/08/98	
	6,197,604	03/06/01	Miller et al.			10/01/98	
	6,204,165	03/20/01	Ghoshal			06/24/99	
	6,210,983	04/03/01	Atchison et al.			06/15/99	
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	6,236,903	05/22/01	Kim et al.			09/25/98	
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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
FOREIGN PATENT DOCUMENTS							
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						Yes	No
	61-66104	04/04/86	Japan			X	
	61-171147	08/01/86	Japan			X	
	01-283934	11/15/89	Japan			X	
	2,050,247	08/29/91	Canada			X	
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	05-216896	08/27/93	Japan			X	
	05-266029	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
	06-184434	07/05/94	Japan			X	
	06-252236	09/09/94	Japan			X	
	06-260380	09/16/94	Japan			X	
	EP 0 621 522 A2	10/26/94	Europe			X	
	WO 95/34866	12/21/95	WO			X	
	8-23166	01/23/96	Japan			X	
	08-50161	02/20/96	Japan			X	
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	09-34535	02/07/97	Japan			X	
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	EP 0 869 652	10/07/98	Europe			X	
	WO 98/45090	10/15/98	WO			X	
	EP 0 877 308 A2	11/11/98	Europe			X	
	EP 0 881 040 A2	12/02/98	Europe			X	
	EP 0 895 145 A1	02/03/99	Europe			X	
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	11-67853	03/09/99	Japan			X	
	EP 0 910 123	04/21/99	Europe			X	
	11-126816	05/11/99	Japan			X	
	11-135601	05/21/99	Japan			X	
	WO 99/25520	05/27/99	WO			X	
	EP 0 932 194	07/28/99	Europe			X	
	WO 00/00874	01/06/00	WO			X	
	WO 00/05759	02/03/00	WO			X	
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	GB 2 347 885 A	09/20/00	United Kingdom			X	
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	EP 1 067 757 A1	01/10/01	Europe			X	
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	WO 01/25865	04/12/01	WO			X	
	EP 1 092 505 A2	04/18/01	Europe			X	
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	436383	05/28/01	Taiwan			X	
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